



100% Material Declaration Data Sheet VO48

PK176 (v2.0) February 12, 2008

Material Declaration Data Sheet

Average Weight: 0.543 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.017912	3.29%
	Silicon	7440-21-3	99.60		0.01784	
	Aluminum	7429-90-5	0.40		0.000072	
Die Attach Material (adhesive)					0.00843	1.55%
	Silver	7440-22-4	77.00		0.00629	
	Bismaleimide polymer	13676-54-5	14.00		0.0014	
	Epoxy resin(EP)	29690-82-2	9.00		0.00074	
Encapsulation					0.41782	76.94%
	Epoxy Resin (EP)	85954-11-6	7.00		0.02716	
	Silica	60676-86-0	89.00		0.37186	
	Phenol Resin	205830-20-2	5.00		0.0188	
Leadframe					0.09533	17.55%
	Copper	7440-50-8	97.00		0.09272	
	Iron	7439-89-6	2.00		0.00228	
	Zinc	7440-66-6	0.1		0.00011	
	Phosphorus	7723-14-0	0.03		0.00003	
	Silver	7440-22-4	0.2		0.00019	
Bond Wire					0.00076	0.14%
	Gold	7440-57-5	100.00		0.00076	
Ext. Plating					0.00314	0.57%
	Tin	7440-31-5	85.00		0.00267	
	Lead	7439-92-1	15.00		0.00047	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/29/06	1.0	Initial release.
2/12/08	2.0	Rewrite 100% Material Declaration; material content change.